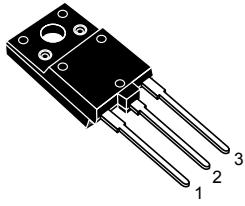
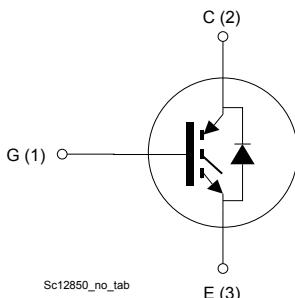


Trench gate field-stop IGBT, V series 600 V, 30 A very high speed

Features

- Maximum junction temperature: $T_J = 175 \text{ }^{\circ}\text{C}$
- Tail-less switching off
- $V_{CE(\text{sat})} = 1.85 \text{ V (typ.)} @ I_C = 30 \text{ A}$
- Tight parameter distribution
- Safe paralleling
- Low thermal resistance
- Very fast soft recovery antiparallel diode


TO-3PF


Sc12850_no_tab

Applications

- Photovoltaic inverters
- Uninterruptible power supply
- Welding
- Power factor correction
- Very high frequency converters

Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the V series IGBTs, which represent an optimum compromise between conduction and switching losses to maximize the efficiency of very high frequency converters. Furthermore, the positive $V_{CE(\text{sat})}$ temperature coefficient and very tight parameter distribution result in safer paralleling operation.



Product status link

[STGFW30V60DF](#)

Product summary

Order code	STGFW30V60DF
Marking	G30V60DF
Package	TO-3PF
Packing	Tube

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage ($V_{GE} = 0$ V)	600	V
I_C	Continuous collector current at $T_C = 25$ °C	60	A
	Continuous collector current at $T_C = 100$ °C	30	
$I_{CP}^{(1)}$	Pulsed collector current	120	A
V_{GE}	Gate-emitter voltage	± 20	V
I_F	Continuous forward current at $T_C = 25$ °C	60	A
	Continuous forward current at $T_C = 100$ °C	30	
$I_{FP}^{(1)}$	Pulsed forward current	120	A
P_{TOT}	Total power dissipation at $T_C = 25$ °C	92	W
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink ($t = 1$ s, $T_C = 25$ °C)	3.5	kV
T_{STG}	Storage temperature range	- 55 to 150	°C
T_J	Operating junction temperature range	- 55 to 175	

1. Pulse width limited by maximum junction temperature.

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance, junction-to-case IGBT	1.63	°C/W
	Thermal resistance, junction-to-case diode	2.55	
R_{thJA}	Thermal resistance, junction-to-ambient	50	°C/W

2 Electrical characteristics

$T_C = 25^\circ\text{C}$ unless otherwise specified.

Table 3. Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{CES}}$	Collector-emitter breakdown voltage	$V_{GE} = 0 \text{ V}, I_C = 2 \text{ mA}$	600			V
$V_{CE(\text{sat})}$	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}, I_C = 30 \text{ A}$		1.85	2.30	V
		$V_{GE} = 15 \text{ V}, I_C = 30 \text{ A}, T_J = 125^\circ\text{C}$		2.15		
		$V_{GE} = 15 \text{ V}, I_C = 30 \text{ A}, T_J = 175^\circ\text{C}$		2.35		
V_F	Forward on-voltage	$I_F = 30 \text{ A}$		2.0	2.6	V
		$I_F = 30 \text{ A}, T_J = 125^\circ\text{C}$		1.7		
		$I_F = 30 \text{ A}, T_J = 175^\circ\text{C}$		1.5		
$V_{GE(\text{th})}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 1 \text{ mA}$	5	6	7	V
I_{CES}	Collector cut-off current	$V_{GE} = 0 \text{ V}, V_{CE} = 600 \text{ V}$			25	μA
I_{GES}	Gate-emitter leakage current	$V_{CE} = 0 \text{ V}, V_{GE} = \pm 20 \text{ V}$			250	nA

Table 4. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	$V_{CE} = 25 \text{ V}, f = 1 \text{ MHz}, V_{GE} = 0 \text{ V}$	-	3750	-	pF
C_{oes}	Output capacitance		-	120	-	pF
C_{res}	Reverse transfer capacitance		-	77	-	pF
Q_g	Total gate charge	$V_{CC} = 480 \text{ V}, I_C = 30 \text{ A}, V_{GE} = 0 \text{ to } 15 \text{ V}$ (see Figure 28. Gate charge test circuit)	-	163	-	nC
Q_{ge}	Gate-emitter charge		-	28	-	nC
Q_{gc}	Gate-collector charge		-	72	-	nC

Table 5. IGBT switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 30 \text{ A}, R_G = 10 \Omega, V_{GE} = 15 \text{ V}$ (see Figure 27. Test circuit for inductive load switching)	-	45	-	ns
t_r	Current rise time		-	16	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1500	-	A/μs
$t_{d(off)}$	Turn-off delay time		-	189	-	ns
t_f	Current fall time		-	19	-	ns
$E_{on}^{(1)}$	Turn-on switching energy		-	383	-	μJ
$E_{off}^{(2)}$	Turn-off switching energy		-	233	-	μJ
E_{ts}	Total switching energy		-	616	-	μJ
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 30 \text{ A}, R_G = 10 \Omega, V_{GE} = 15 \text{ V}, T_J = 175 \text{ °C}$ (see Figure 27. Test circuit for inductive load switching)	-	42	-	ns
t_r	Current rise time		-	17	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1337	-	A/μs
$t_{d(off)}$	Turn-off delay time		-	193	-	ns
t_f	Current fall time		-	32	-	ns
$E_{on}^{(1)}$	Turn-on switching energy		-	794	-	μJ
$E_{off}^{(2)}$	Turn-off switching energy		-	378	-	μJ
E_{ts}	Total switching energy		-	1172	-	μJ

1. Including the reverse recovery of the diode.
2. Including the tail of the collector current.

Table 6. Diode switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$I_F = 30 \text{ A}, V_R = 400 \text{ V}, V_{GE} = 15 \text{ V}, di/dt = 1000 \text{ A/μs}$ (see Figure 27. Test circuit for inductive load switching)	-	53	-	ns
Q_{rr}	Reverse recovery charge		-	384	-	nC
I_{rrm}	Reverse recovery current		-	14.5	-	A
dl_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	788	-	A/μs
E_{rr}	Reverse recovery energy		-	104	-	μJ
t_{rr}	Reverse recovery time	$I_F = 30 \text{ A}, V_R = 400 \text{ V}, V_{GE} = 15 \text{ V}, di/dt = 1000 \text{ A/μs}, T_J = 175 \text{ °C}$ (see Figure 27. Test circuit for inductive load switching)	-	104	-	ns
Q_{rr}	Reverse recovery charge		-	1352	-	nC
I_{rrm}	Reverse recovery current		-	26	-	A
dl_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	310	-	A/μs
E_{rr}	Reverse recovery energy		-	407	-	μJ

2.1 Electrical characteristics (curves)

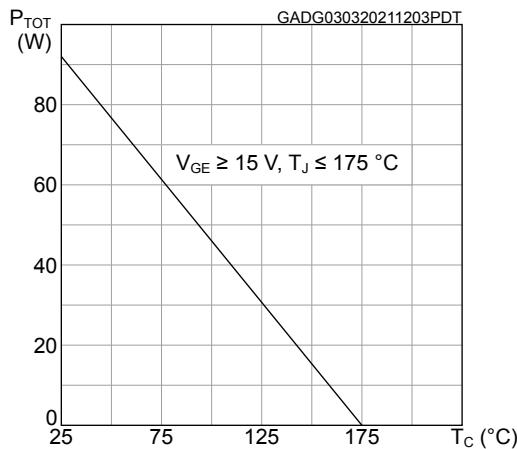
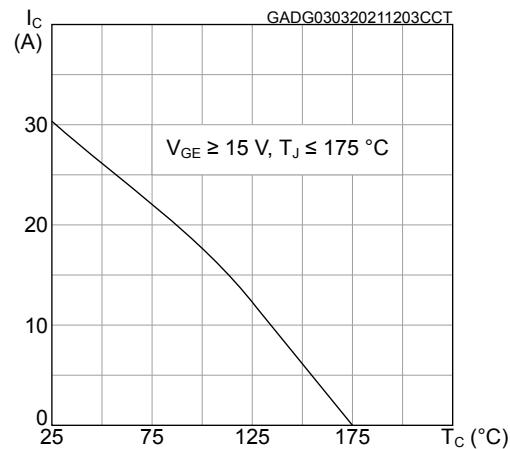
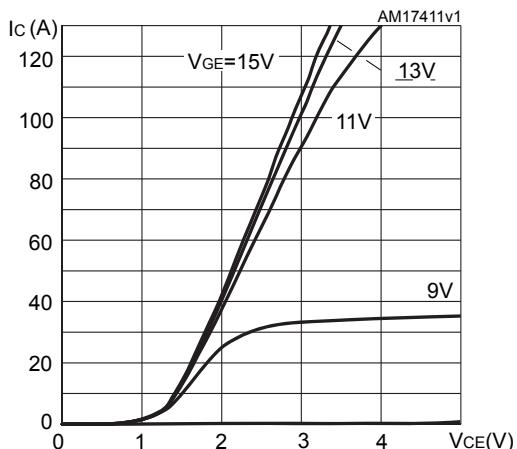
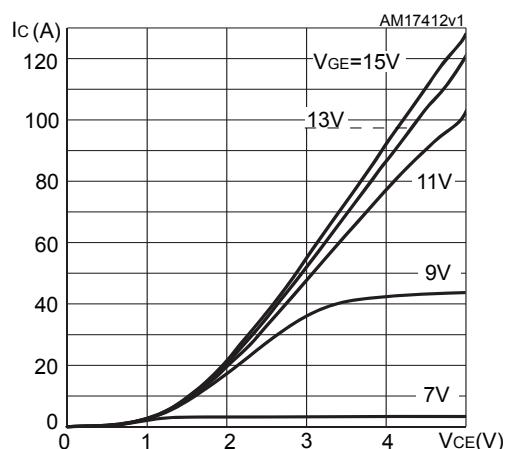
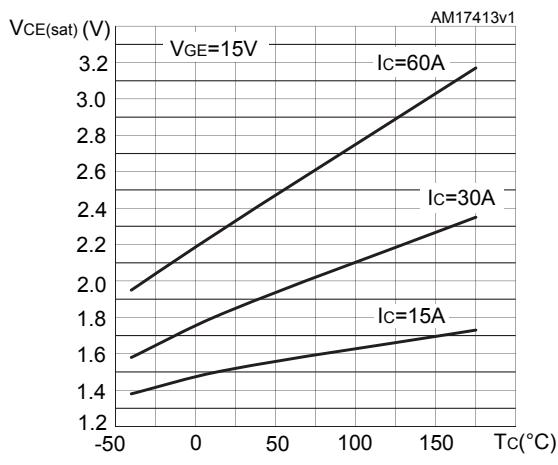
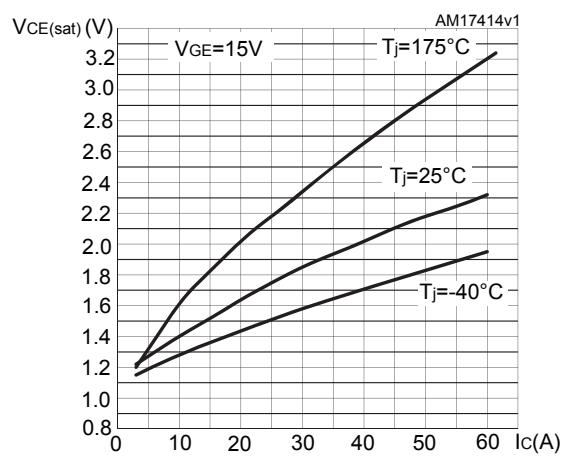
Figure 1. Power dissipation vs case temperature

Figure 2. Collector current vs case temperature

Figure 3. Output characteristics ($T_J = 25$ °C)

Figure 4. Output characteristics ($T_J = 175$ °C)

Figure 5. $V_{CE(sat)}$ vs junction temperature

Figure 6. $V_{CE(sat)}$ vs collector current


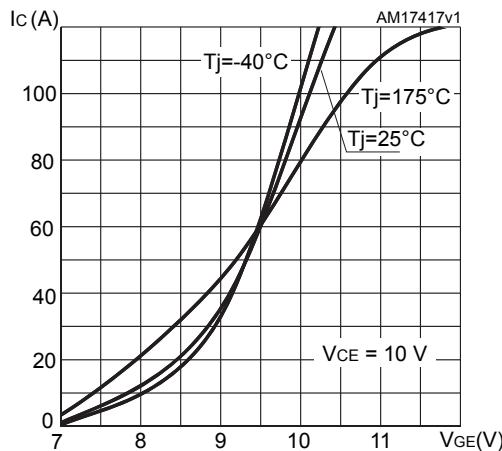
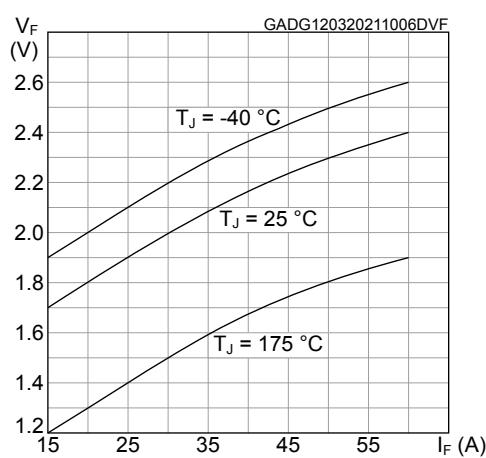
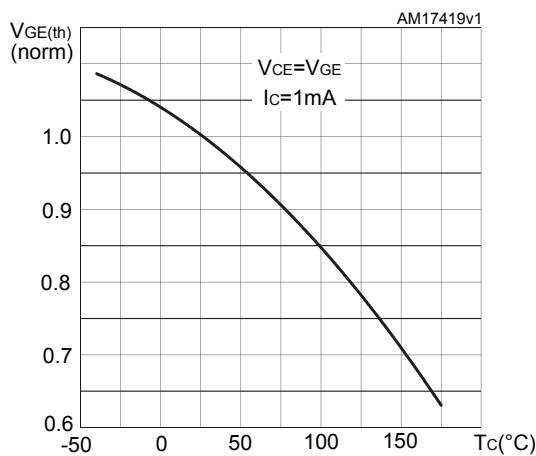
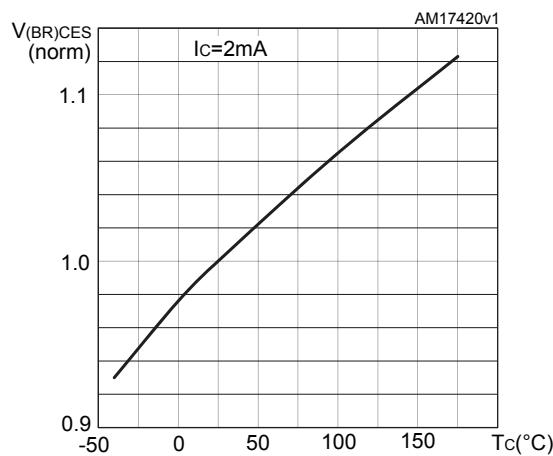
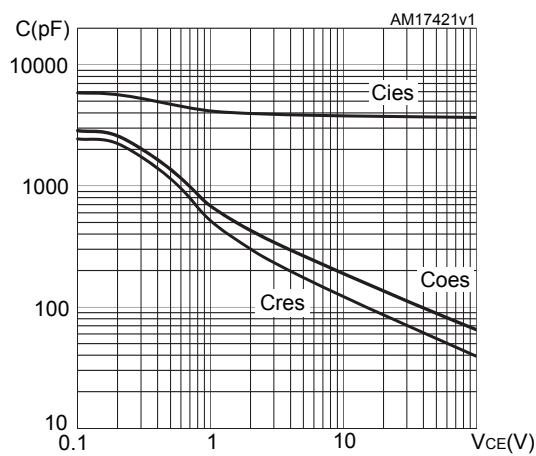
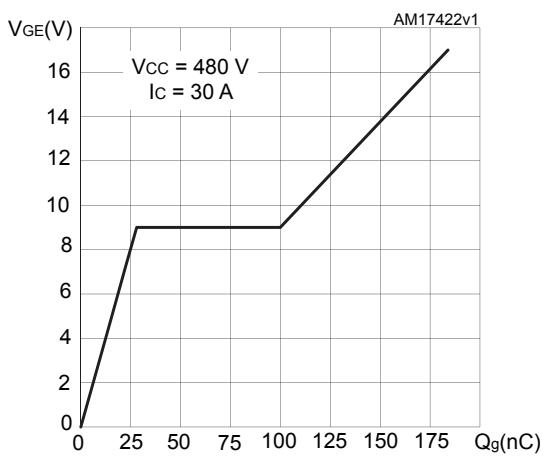
Figure 7. Transfer characteristics

Figure 8. Diode V_F vs forward current

Figure 9. Normalized $V_{GE(\text{th})}$ vs junction temperature

Figure 10. Normalized $V_{(BR)CES}$ vs junction temperature

Figure 11. Capacitance variations

Figure 12. Gate charge vs gate-emitter voltage


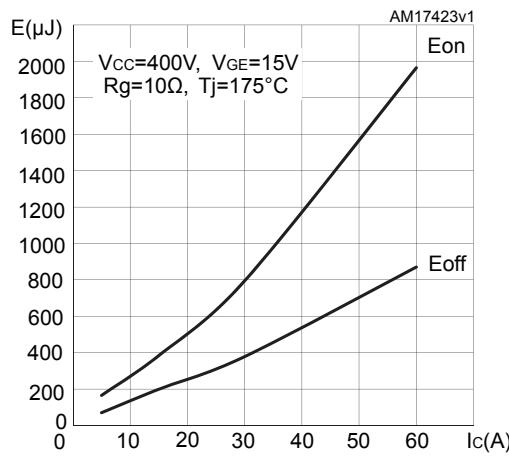
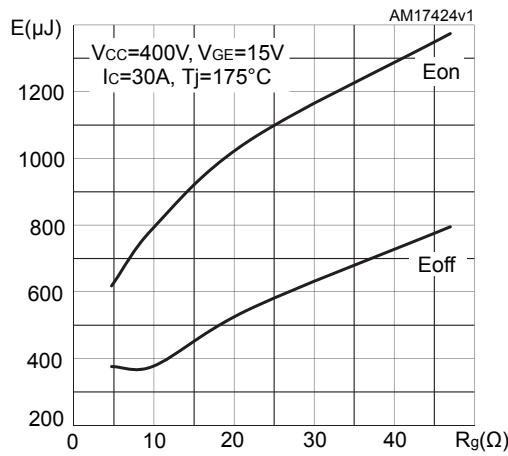
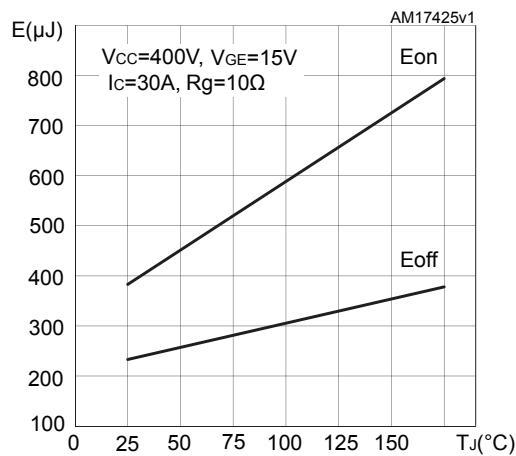
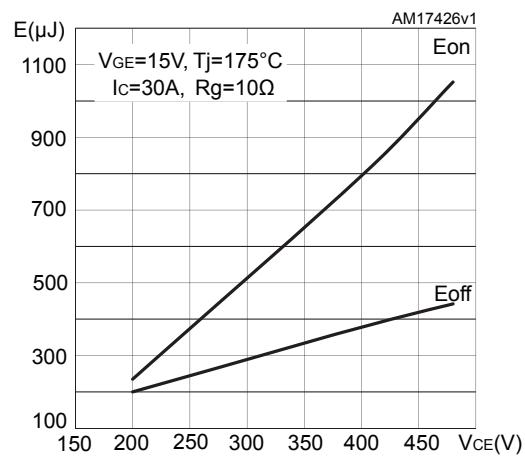
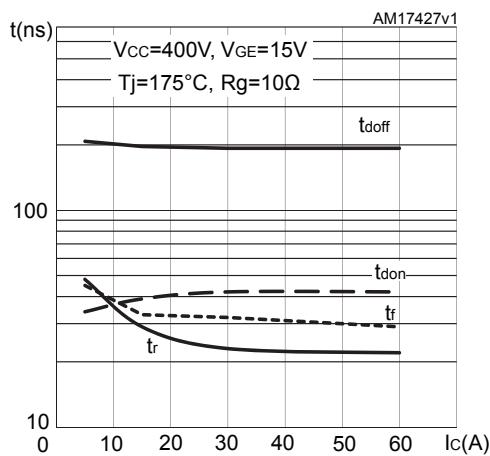
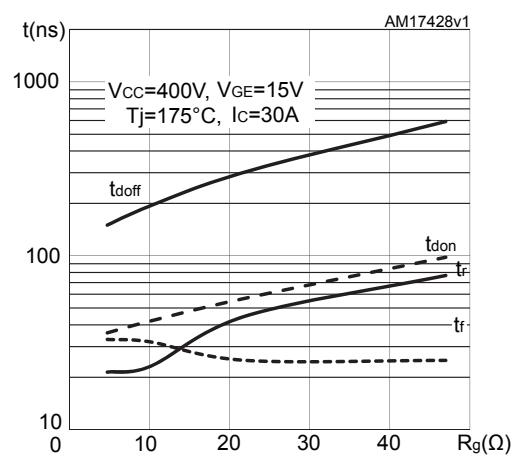
Figure 13. Switching energy vs collector current

Figure 14. Switching energy vs gate resistance

Figure 15. Switching energy vs junction temperature

Figure 16. Switching energy vs collector-emitter voltage

Figure 17. Switching times vs collector current

Figure 18. Switching times vs gate resistance


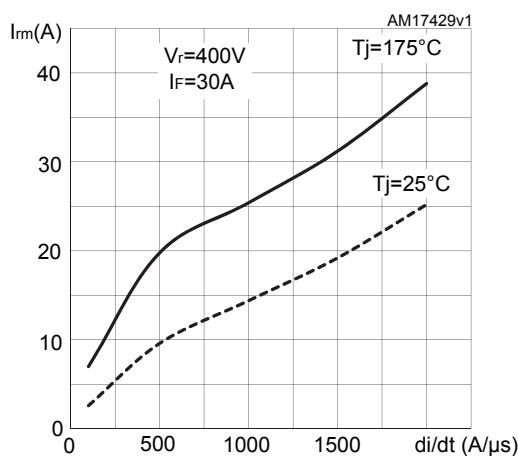
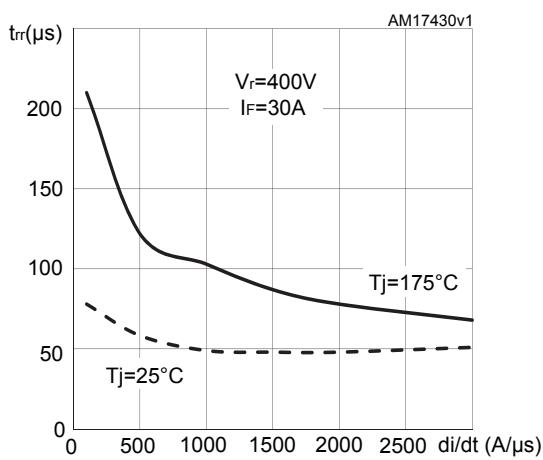
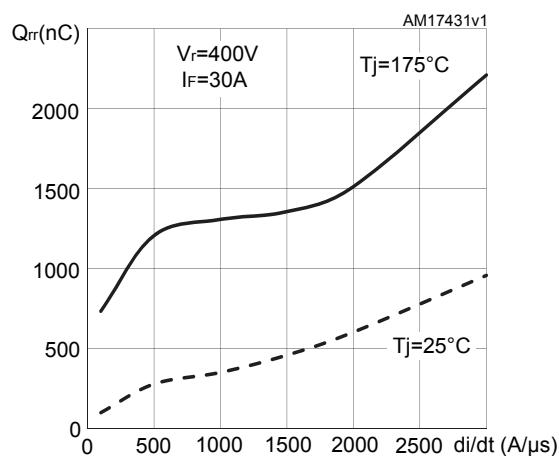
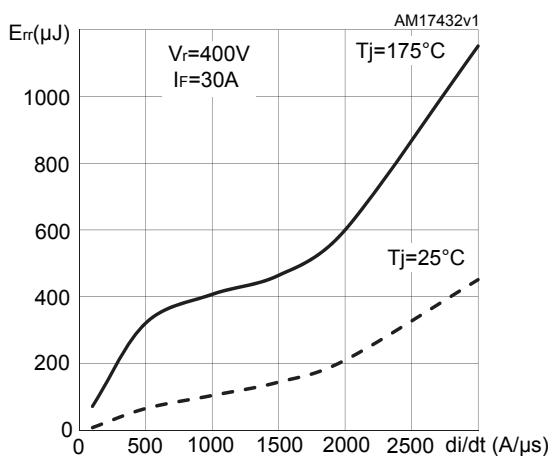
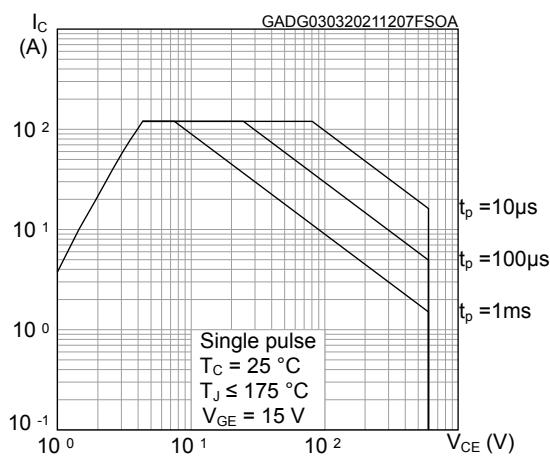
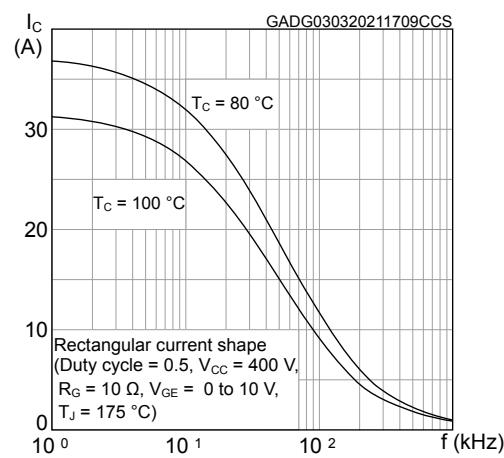
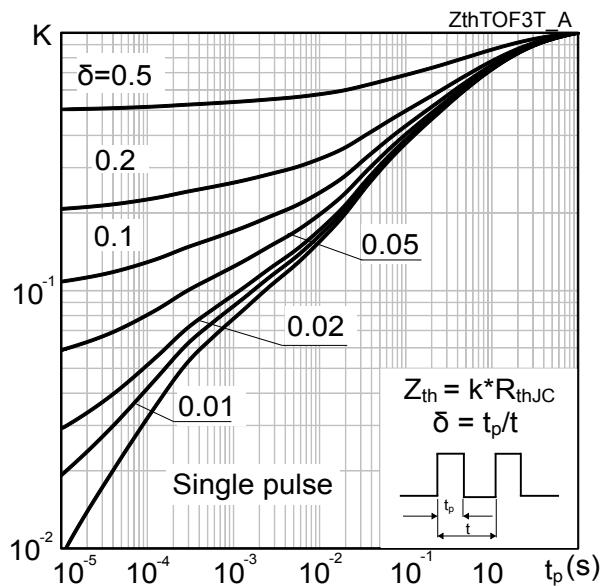
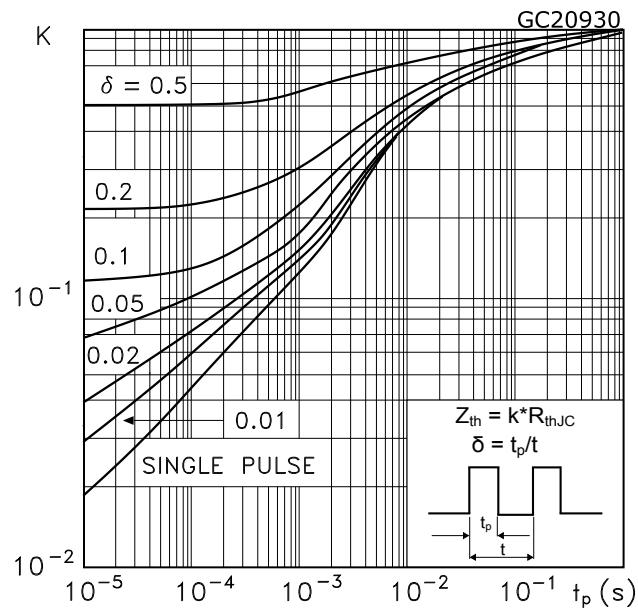
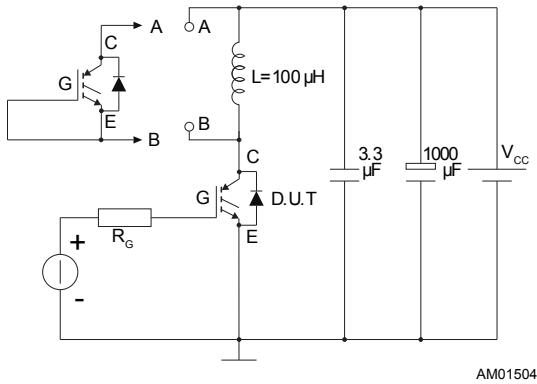
Figure 19. Reverse recovery current vs diode current slope

Figure 20. Reverse recovery time vs diode current slope

Figure 21. Reverse recovery charge vs diode current slope

Figure 22. Reverse recovery energy vs diode current slope

Figure 23. Safe operating area

Figure 24. Collector current vs switching frequency


Figure 25. Thermal impedance for IGBT**Figure 26. Thermal impedance for diode**

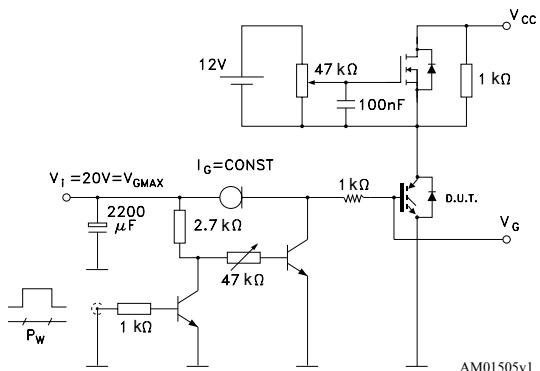
3 Test circuits

Figure 27. Test circuit for inductive load switching



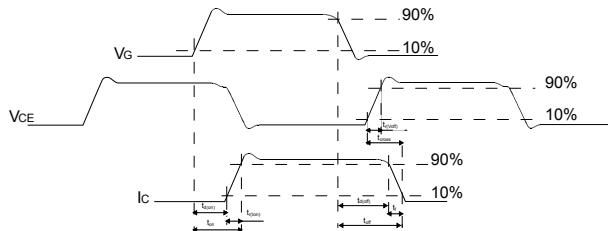
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Figure 28. Gate charge test circuit



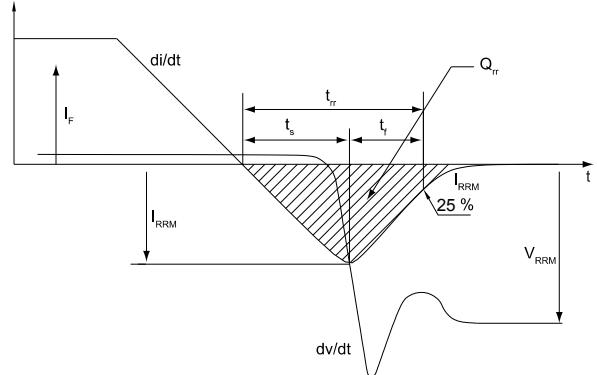
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Figure 29. Switching waveform



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Figure 30. Diode reverse recovery waveform



AM01507v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 TO-3PF package information

Figure 31. TO-3PF package outline

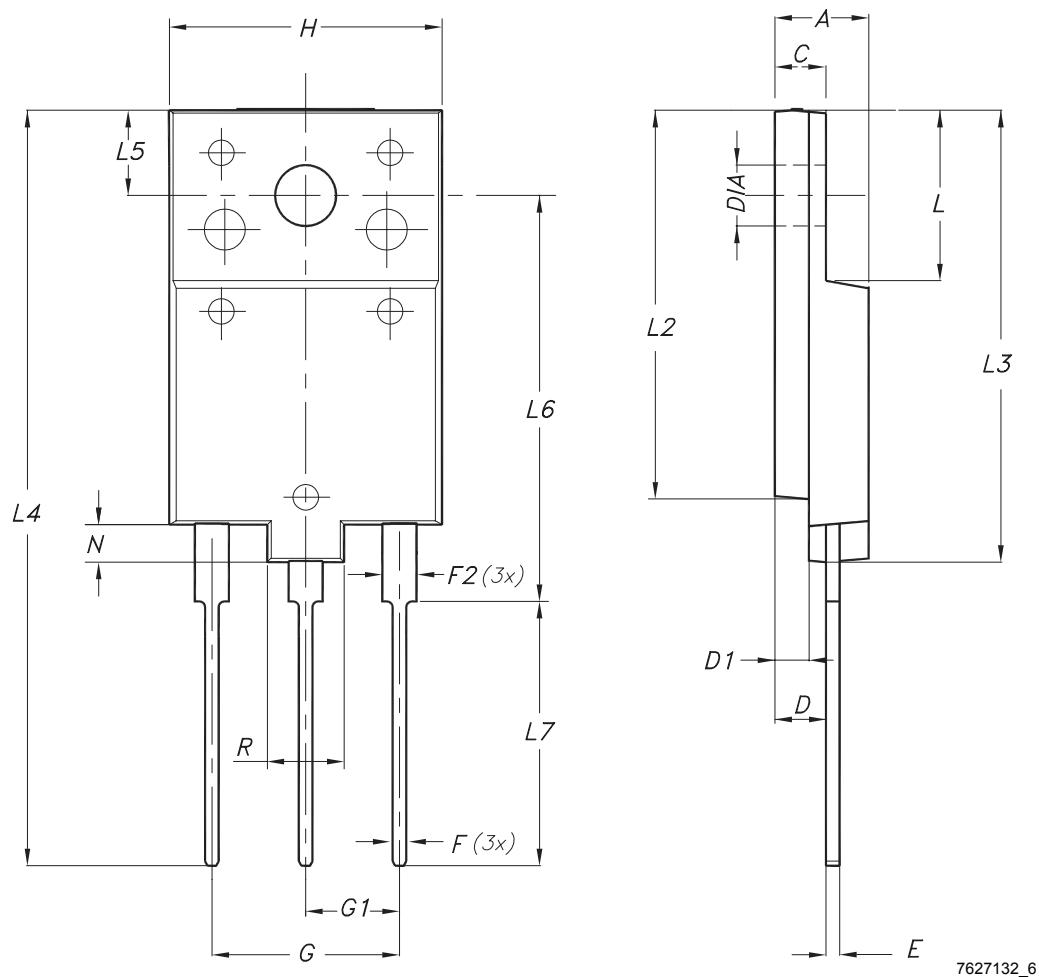


Table 7. TO-3PF mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	5.30		5.70
C	2.80		3.20
D	3.10		3.50
D1	1.80		2.20
E	0.80		1.10
F	0.65		0.95
F2	1.80		2.20
G	10.30		11.50
G1		5.45	
H	15.30		15.70
L	9.80	10.00	10.20
L2	22.80		23.20
L3	26.30		26.70
L4	43.20		44.40
L5	4.30		4.70
L6	24.30		24.70
L7	14.60		15.00
N	1.80		2.20
R	3.80		4.20
Dia	3.40		3.80

Revision history

Table 8. Document revision history

Date	Revision	Changes
31-Mar-2014	1	Initial release.
14-Apr-2020	2	Updated <i>Section Product status / summary</i> in cover page. Minor text changes.
12-Mar-2021	3	Updated <i>Section 1 Electrical ratings</i> . Updated <i>Table 3. Static characteristics</i> . Updated <i>Figure 1. Power dissipation vs case temperature</i> , <i>Figure 2. Collector current vs case temperature</i> , <i>Figure 8. Diode V_F vs forward current</i> , <i>Figure 23. Safe operating area</i> and added <i>Figure 24. Collector current vs switching frequency</i> . Minor text changes.

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[APT70GR120JD60](#) [AOD5B60D](#)